Brian Benchoff

Embedded Engineer

Experience

Vocational

2011-2018 **Editor**, *Hackaday*, Pasadena, CA.
Wrote, edited, produced content for weblog Hackaday. Designed hardware products and projects.

2018-Present **Content Specialist**, *Supplyframe*, Pasadena, CA.
Produced electronic design and engineering content, engaged with engineers regarding new products. Responsible for hardware projects, PCB & firmware design. 3D modeling, injection molded and 3D printed plastic and silicone.

2016-Present **Embedded Engineer, Product Designer**, *Self-Employed*, San Francisco.
Designed, built, and sold consumer electronics. This included 3D CAD Fusion360, AutoCAD, PCB design Eagle, KiCAD, Design for Manufacturability and Design for Assembly. Closey integrated with PCB assembly, up to and including running pick and place machines. Fabrication of 3D printed and injection molded parts in plastic and silicone. Designed, marketed, and sold several successful products.

Skills

Languages	C, C++, Python, LaTeX, SQL	Graphic	Adobe Photoshop, Illustrator, Premiere
Mechanical CAD	Fusion360, AutoCAD, OpenSCAD	Platforms	x86, 8085, AVR, ARM Cortex-M (M0 & M4), Tensilica, 68000, Linux SoCs (Microchip, Allwinner)
Electronic CAD	Altium, Eagle, KiCAD	Misc	Microsoft Office, 3D Printing, Rapid Prototyping, Industrial Design
Embedded	I2C, SPI, Serial, Parallel interfaces, USB, USB-C, HDMI, PCIe, eMMC	PCB	BGA, Down to 2/2mil trace/space, 010005 components
Embedded Linux	Buildroot, Yocto	Mechanical	Injection molding in plastic and silicone, machining

3033 Rivera St – 94116 San Francisco – USA
+1 (215) 690 1415 • *benchoff@gmail.com*
https://bbenchoff.github.io/ • *bbenchoff* • *bbenchoff*
bbenchoff • *12156901415*